

# RoHS

REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25

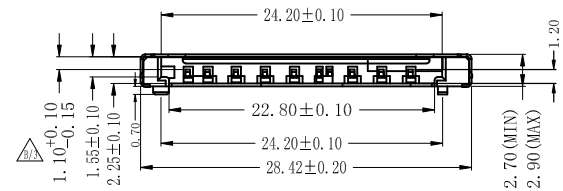
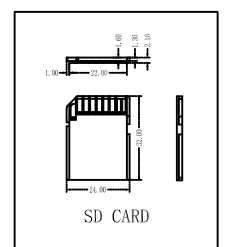
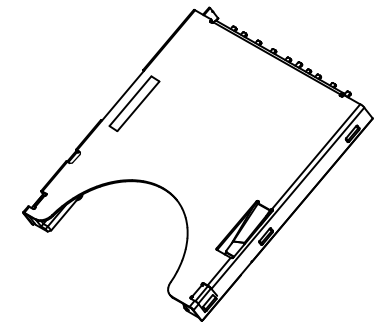
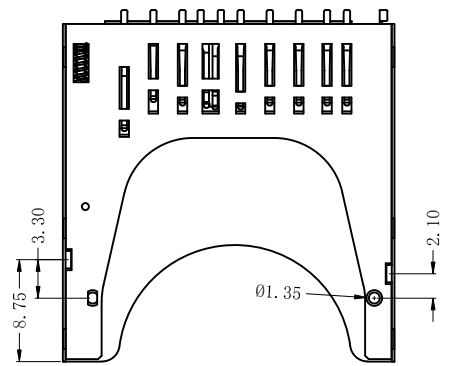
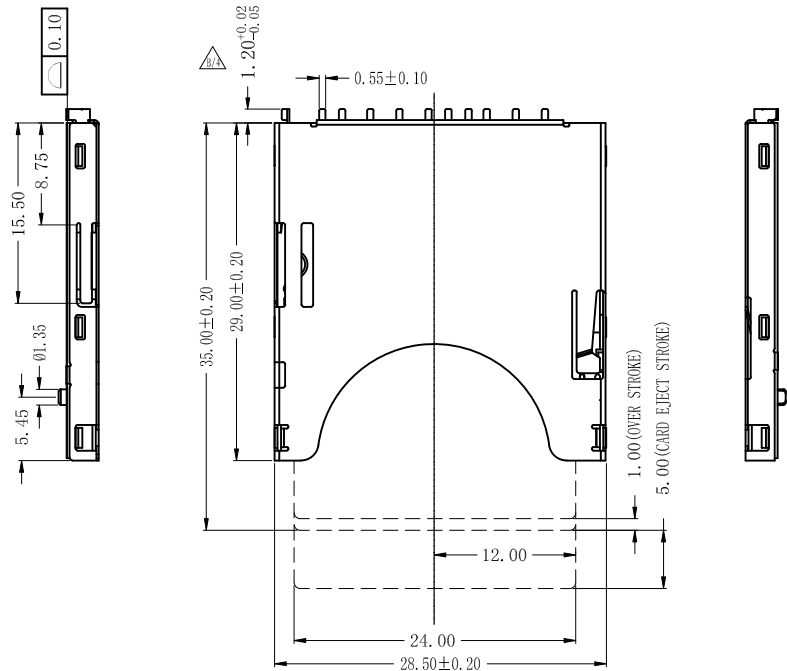
**NOTES :**

- MATERIAL:**  
HOUSING:HIGH TEMPERATURE THERMOPLASTIC UL94V-0, COLOR:BLACK  
CONTACT:COPPER ALLOYS  
COVER: COPPER ALLOYS OR STEEL
- PLATING:**  
UNDERPLATE: NICKEL  
CONTACT AREA: GOLD OVER NICKEL  
SOLDER AREA: TIN OVER NICKEL
- MULTIMEDIA CARD COMPATIBLE**

**订购须知:**

SDP11-N1S1-1000-A  
1 2

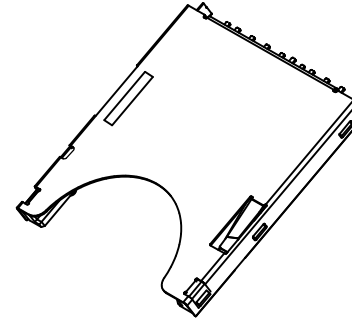
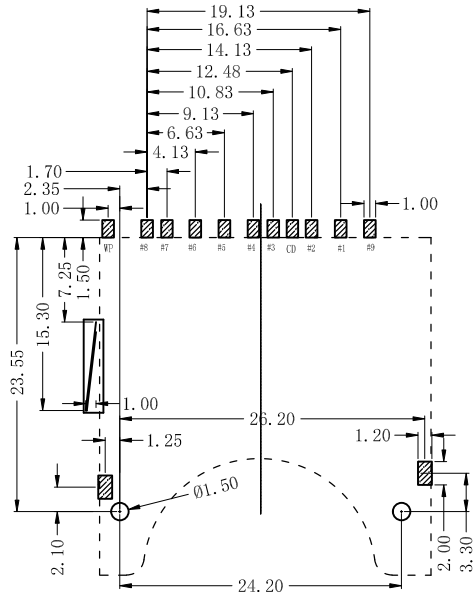
- 电镀方式**  
S1=端子镀半金雾锡  
F1=端子镀全金
- 包装方式**  
1=吸塑盘装  
2=载带装



X.±0.50	X.°±	PART NO: SDP11-N1S1-1000-A	<b>XFCN</b> 兴飞连接器			
.X±0.25	.X°±					
.XX±0.15	.XX°±	TITLE: SD PUSH卡座	0769-82001899			
.XXX±0.10	.XXX°±		www.xfconn.com			
UNITS:	mm	DWG NO:		/		
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		CHKD				
		DRAW	Wang	VIEW		
		DATE	2024.03.07	SCALE	SHEET	REV
			NONE	1:2	A1	

# RoHS

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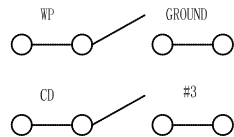
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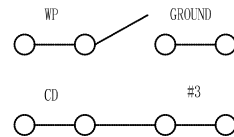
**订购须知:**

SDP11-N1S1-1000-A  
1 2

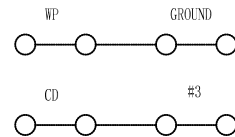
- 1.电镀方式**  
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1=吸塑盘装  
2=载带装



WITHOUT CARD



CARD INSERTED WRITE  
PROJECT:LOCK



CARD INSERTED WRITE  
PROJECT:UNLOCK

SD CARD PIN DESIGN			
PIN NO.	NAME	TYPE	DESCRIPTION
#1	CD/DAT3	I/O/PP	CARD DETECT/DATA LINE(BIT3)
#2	CMD	PP	COMMAND/RESPONSE
#3	VSS1	S	SUPPLY VOL AGE GROUND
#4	VDD	S	SUPPLY VOLTAGE
#5	CLK	I	CLOCK
#6	VSS2	S	SUPPLY VOL AGE GROUND
#7	DAT0	I/O/PP	DATA LINE(BIT 0)
#8	DAT1	I/O/PP	DATA LINE(BIT 1)
#9	DAT2	I/O/PP	DATA LINE(BIT 2)

X.±0.50	X.°±
.X±0.25	.X°±
.XX±0.15	.XX°±
.XXX±0.10	.XXX°±
UNITS:	mm

PART NO: SDP11-N1S1-1000-A	
TITLE: SD PUSH卡座	
APPD	
CHKD	
DRAW	Wang
DATE	2024.03.07

**XFCN 兴飞连接器**

0769-82001899  
www.xfconn.com

DWG NO: /

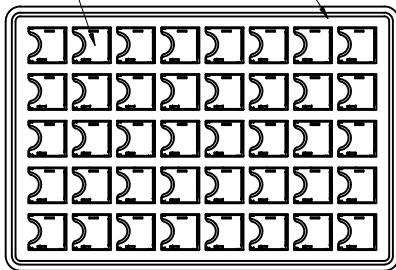
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VIEW	
SCALE	NONE
SHEET	2:2
REV	A1

# RoHS

每盘40PCS

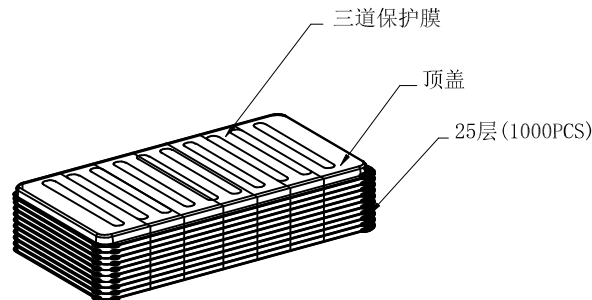
吸塑盘



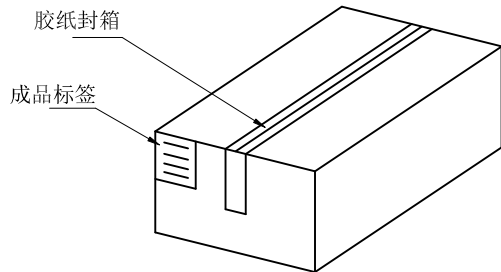
吸塑盘规格: 303\*193\*8mm

NO. 1

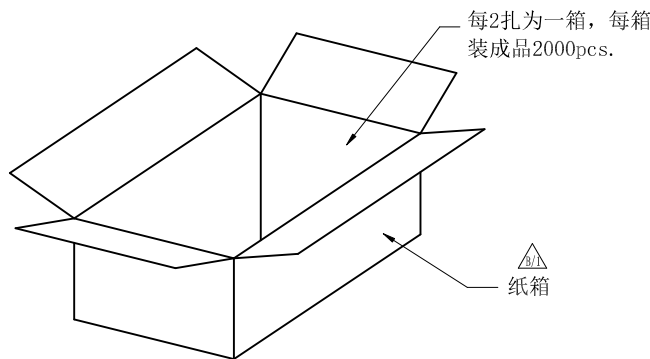
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NO. 2



NO. 4



NO. 3

1. 材质要求:
  - 1.1 纸箱的材质为A=A; 外形尺寸为32\*20.5\*26cm;
  - 1.2 PS盘的材质为PS, PS盘的外形尺寸303\*193\*8mm;
2. 包装要求:
  - 2.1 每一盘装40PCS;
  - 2.2 每25盘累叠在一起, 共计1Kset; 上面需放一个空盘, 后用PE膜缠绕;
  - 2.3 把累叠好的PS盘放入纸箱中;
  - 2.4 把包装好的成品打包封箱, 并在纸箱中贴上标签;

X. $\pm$ 0.50	X. $^{\circ}$ $\pm$	PART NO: SDP11-N1S1-1000-A	<b>XFCN</b> 兴飞连接器		
.X $\pm$ 0.25	.X $^{\circ}$ $\pm$				
.XX $\pm$ 0.15	.XX $^{\circ}$ $\pm$	TITLE: SD PUSH卡座	0769-82001899		
.XXX $\pm$ 0.10	.XXX $^{\circ}$ $\pm$		www.xfconn.com		
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		CHKD		SCALE	SHEET
		DRAW	Wang	NONE	REV
		DATE	2024.03.07		2:2

# XFCN 东莞市兴飞连接器有限公司

部品料号: SDP11-N1S1-1000-A

部品描述: SD PUSH CARD CONNECTOR

## 1. SCOPE 适用范围

This specification covers performance, tests and quality requirements for SD CARD CONNECTOR. These connectors are provide space savings and improved functionality to system signal transfer.

此规范包括性能, 测试及质量要求, 适用于SD安全数字记忆卡连接器, 提供完善的功能系统信号传输。

## 2. APPLICABLE DOCUMENTS 适用文件

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

下列文件构成本规范的一部分, 以本文规定的范围内。除另有规定外, 该规范的最新版本适用。在此规范之间的冲突和产品图纸要求的情况下, 产品图纸为准。

### 2. 1. Commercial standards, specifications and report 商业标准, 规格及报告

2. 1. 1. MIL-STD-1344A 根据MIL - STD - 1344A 标准

2. 1. 2. MIL-STD-202F 根据MIL - STD - 202F标准

## 3. REQUIREMENTS 要求

### 3.1. Design and Construction 设计与装配

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

产品应在设计, 装配和结构尺寸指定适用产品图纸。

### 3.2. Materials and Finish 材料与处理

3. 2. 1. Contact : High performance copper alloy (Phosphor Bronze)

Finish : (a) Contact Area: Gold over Nickel.

(b) Solder Tail area: Tin over Nickel.

端子: 高性能铜合金 (磷青铜)

表面处理: (a) 接触部分: 打镍底, 镀金。

(b) 焊锡区: 打镍底, 镀纯锡。

3. 2. 2. Housing : LCP+30%G.F, UL94V-0.

胶芯材质: LCP +30 % 玻璃纤维, 耐燃指数: UL94V - 0。

SPEC NO.		REV	B/0	ECN NO.		PAGE	1 / 4
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### 3.3. Ratings 评定标准

- 3.3.1. Voltage : 500 Volts DC,AC(rms)250 Volts (per pin)  
耐电压: 500伏特直流, 250伏特交流(rms)
- 3.3.2. Current : 0.5 Amperes DC (per pin)  
最大电流: 0.5安培直流
- 3.3.3. Operating Temperature : -25°C TO +85°C  
使用温度: -25°C至+85°C

### 3.4. Performance and Test Description 性能及测试说明

Product is designed to meet electrical, mechanical and environmental performance requirements specified in Paragraph 3.5. All tests are performed at ambient environmental conditions per MIL-STD-1344A unless otherwise specified.

产品的目的是为了满足不同电气, 机械和环境性能要求在指定的第 3.5 节。所有测试是在常压环境条件按照 MIL - STD- 1344A 完成除非另有说明。

### 3.5. Test Requirements and Procedures Summary 测试要求和程序说明。

Test Description 测试说明	Finally 测试结果	Condition 测试条件
<b>ELECTRICAL (电气)</b>		
Low-Signal Level Contact Resistance 接触电阻测试	R<80 mΩ 电阻小于 80mΩ	Mate subject connector with compatible connector as shown in. MIL-STD-202F, Method 302 500±10 %伏特之间的相邻或接触交配连接器为一分钟。 根据MIL - STD - 202F ,方法302。
Insulation Resistance 绝缘电阻测试	R>1000 MΩ 绝缘电阻大于1000MΩ	Apply DC 500±10% Volts between adjacent contacts of mated connectors for one minute. MIL-STD-202F, Method 302 500±10 %伏特之间的相邻或接触交配连接器为一分钟。 根据 MIL - STD - 202F,方法 302。
Dielectric Withstanding Voltage 介质耐电压	No discharge, flashover or breakdown. 没有放电, 烧焦或击穿。	500 V initial and 250 Vfinal for 1 minute. MIL-STD-202F, Method 301 500V 和 250V 持续一分钟。 根据 MIL - STD - 202F,方法 301。

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<b>Retention Force</b> 端子保持力	100 Gram(0.98N) minimum(per pin) 每 pin 最小 100 克 ( 0.98N ) 。	Mate connector with a suitable gauge for each pin at rate of 25 mm/min. MIL-STD-1344A, Method 2012.1 用连接器与一个合适的拉力计，每个管脚在速度为 25 毫米/每分钟情况下。 根据 MIL - STD - 1344A，方法 2012.1					
<b>Vibration</b> 振动测试	Discontinuity 1.0 microsec. MAX 瞬断不超过1毫秒。	Mate dummy card and subject to following Vibration conditions for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1 mA during Amplitude: 1.52 mm P-P Frequency: 10-55-10 Hz Shall be traversed in 1 minute (MIL STD – 202 Method 201) 振幅： 1.52毫米P-P 频率： 10-55-10赫兹 每种频率持续一分种循环					
<b>Durability</b> 寿命周期测试	5000 cycles. 插拔 5000 次。	The sample should be mounted in the at the rate of 25mm/min. MIL-STD-1344A, Method 2016 样品应装在试验机，在指定的速 25mm/min。 根据 MIL - STD - 1344A，方法 2016					
<b>Solderability</b> 可焊性测试	Solderable area shall have minimum of 95% solder coverage. 可焊面积大于 95 %	Subject the test area of contacts into flux for 3±0.5 seconds and then into solder bath, controlled at 270±5℃, for 3±0.5 seconds. 持需焊部分放入锡炉，温度控制在270 ± 5 ℃，为3 ± 0.5秒。					
<b>ENVIRONMENTAL (环境)</b>							
<b>Salt Spray</b> 氧化测试	Oxidation of not more than 5%. 氧化面积不超过5%。	Subject mated/unmated connectors to 5±1% salt-solution concentration, 35℃±2℃ for 24 hours ( Gold over for 24 H, Nickel for 24 H, Tin for 8 H ) . MTL-STD-1344A, Method 1001.1, 以5 ± 1 % 的盐溶液浓度，35 ℃ ± 2 ℃，24小时(镀金区域24小时，镀镍区域24小时，镀锡区域8小时)。 MTL-STD-1344A 1001.1					
SPEC NO.		REV	B/0	ECN NO.		PAGE	3 / 4

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<p>Temperature Life (Heat Aging) (Heat Resistance) 高温测试 (热老化) (耐热)</p>	<p>A. Products in <math>85\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}</math> 96 hours, the product can still be used normally. B. Products in the <math>255\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}</math> or eight of the reflow temperature (10 second), the deformation of not more than 0.12 mm. A. 产品在<math>85^{\circ}\text{C} \pm 2^{\circ}\text{C}</math> 96小时，产品仍可正常使用。 B. 产品经过八温段回流焊最高温度在<math>255^{\circ}\text{C} \pm 5^{\circ}\text{C}</math> (10秒)，变形不超过0.12mm。</p>	<p>MTL-STD-202F, Method 108A,</p>					
SPEC NO.		REV	B/0	ECN NO.		PAGE	4 / 4

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